

Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low RDS(ON)

Product Summary



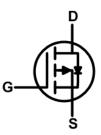
BVDSS	RDSON	ID
-100V	115mΩ	-15A

Applications

- Battery switching application
- Hard switched and high frequency circuits
- Power management

PDFN3333-8L Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	-100	V	
V _G s	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	-15	А	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	-9.2	А	
I _{DM}	Pulsed Drain Current ²	-58	Α	
EAS	Single Pulse Avalanche Energy ³		mJ	
las	Avalanche Current		А	
P _D @T _C =25°C	Total Power Dissipation ⁴	69	W	
T _{STG}	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit	
Reja	Thermal Resistance Junction-Ambient ¹		75	°C/W	
Rejc	Thermal Resistance Junction-Case ¹		1.8	°C/W	



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =-250uA	-100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient Reference to 25°C , I _D =1mA					V/°C
В	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-5A		115	150	m()
R _{DS(ON)}	Static Drain-Source On-Resistance-	V _{GS} =-4.5V , I _D =-5A		130	165	- mΩ
V _{GS(th)}	Gate Threshold Voltage	\\ -\\ - 250\	-1.2	-1.7	-2.2	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=-250uA$				mV/°C
	Drain-Source Leakage Current	V _{DS} =-100V , V _{GS} =0V , T _J =25°C			1	uA
I _{DSS}	Diain-Source Leakage Current	V _{DS} =-100V, V _{GS} =0V , T _J =100°C				uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS} = \pm 20V$, $V_{DS} = 0V$			±100	nA
gfs	Forward Transconductance	orward Transconductance V _{DS} =-10V , I _D =-5A				S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz				Ω
Qg	Total Gate Charge	al Gate Charge		12.7		
Q _{gs}	Gate-Source Charge V _{DS} =-50V , V _{GS} =-10V , I _D =-5A			2.1		nC
Q_{gd}	Gate-Drain Charge			2.3		
T _{d(on)}	Turn-On Delay Time			5.9		
Tr	Rise Time	V _{GS} =-10V, V _{DS} =-50V,		3.7		
T _{d(off)}	Turn-Off Delay Time	I_D =-5A, R_G =5 Ω		39.5		ns
T _f	Fall Time			24.6		
C _{iss}	Input Capacitance			700		
C _{oss}	Output Capacitance	V _{DS} =-50V , V _{GS} =0V , f=1MHz		56		pF
C _{rss}	Reverse Transfer Capacitance			8.6		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current ^{1,4}	V _G =V _D =0V , Force Current			-15	А
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =-5A , T _J =250			-1.2	V
t _{rr}	Reverse Recovery Time	IF=-5A , di/dt=100A/		66		nS
Qrr	Reverse Recovery Charge	µs , TJ=250		214		nC

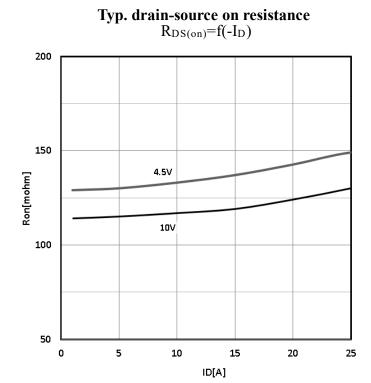
Notes

1. Repetitive rating; pulse width limited by maximum junction temperature



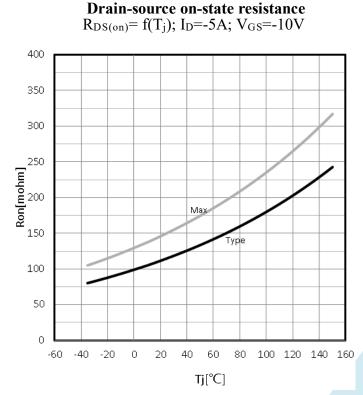
Characteristics Curve:

Typ. output characteristics $-I_D = f(-V_{DS})$



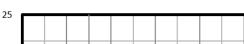
Typ. transfer characteristics $-I_D=f(-V_{GS})$

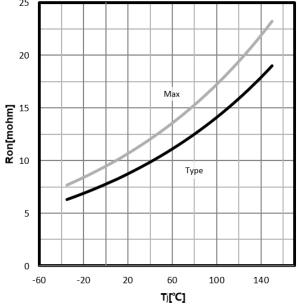
-Vgs[V]



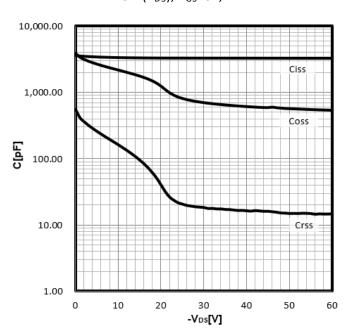


Drain-source on-state resistance $R_{DS(on)}=f(T_j); I_D=-20A; V_{GS}=-10V$

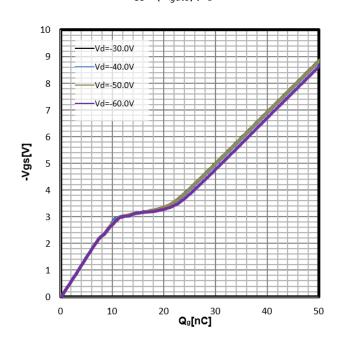




Typ. capacitances $C = f(V_{DS}); V_{GS} = 0V; f = 1MHz$

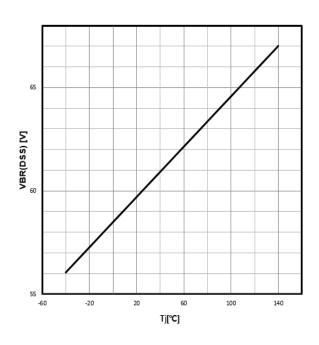


Typ. gate charge V_{GS} = $f(Q_{gate})$; I_D =-20A

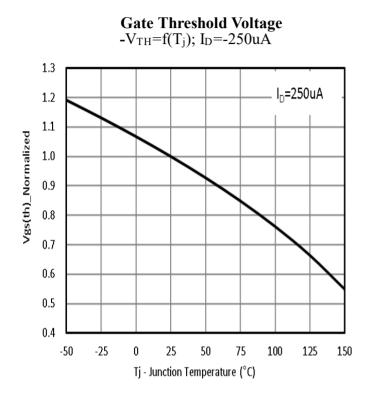


Drain-source breakdown voltage

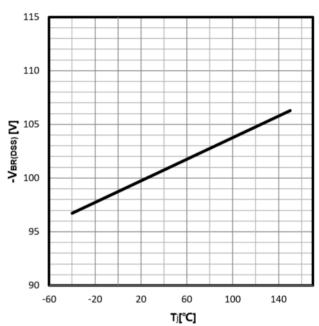
 $V_{BR(DSS)}=f(T_j); I_D=-250uA$

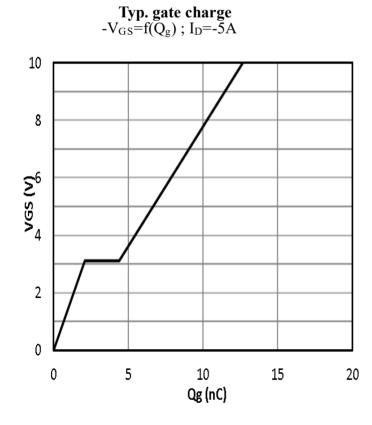


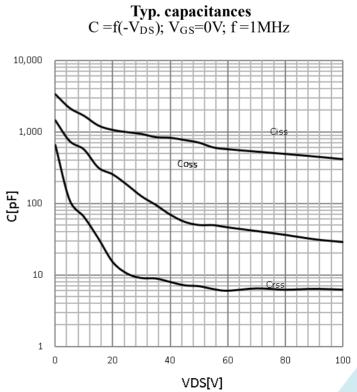




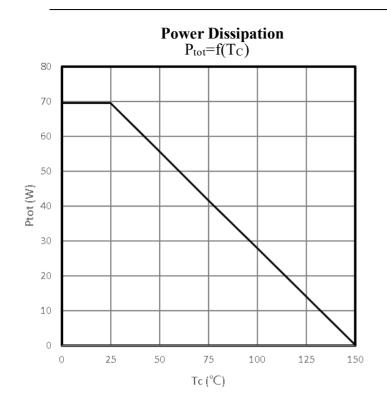
 $\begin{array}{c} \textbf{Drain-source breakdown voltage} \\ \textbf{-}V_{BR(DSS)} \text{=} f(T_j); \ I_D \text{=-} 250 uA \end{array}$

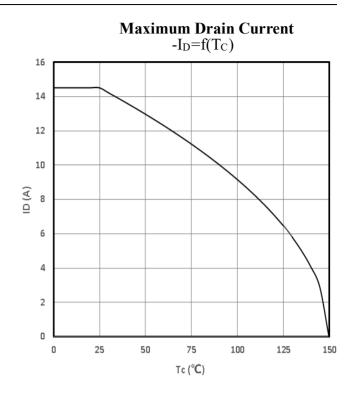


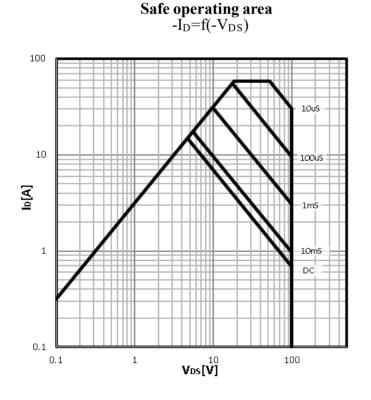


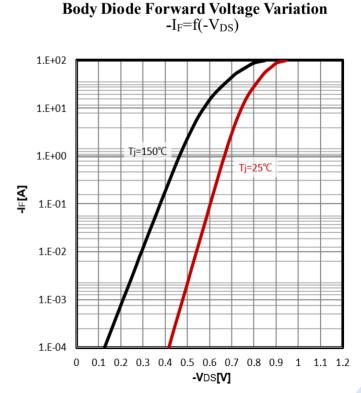




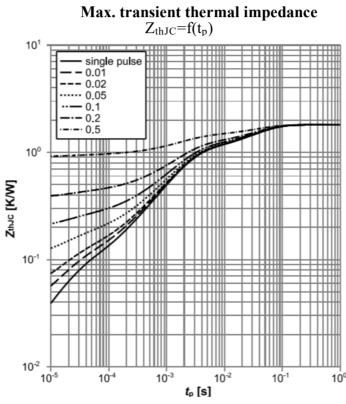








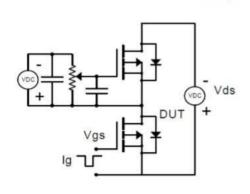


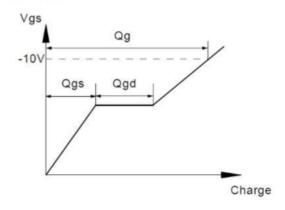




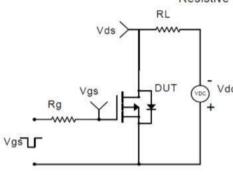
Test Circuit and Waveform:

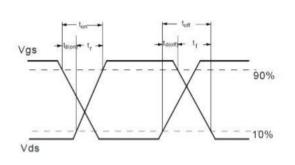
Gate Charge Test Circuit & Waveform



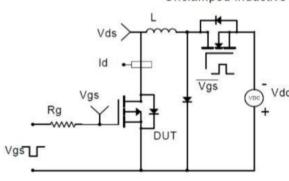


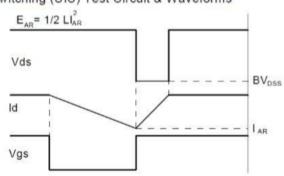
Resistive Switching Test Circuit & Waveforms



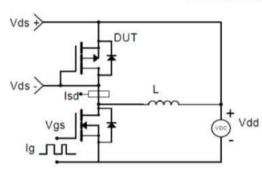


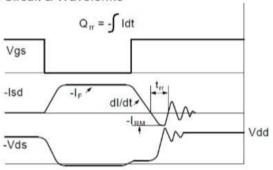
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





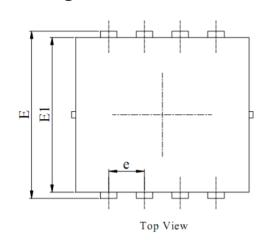
Diode Recovery Test Circuit & Waveforms

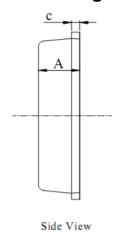


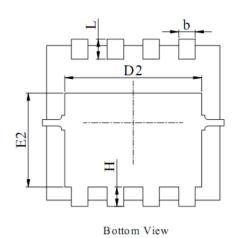


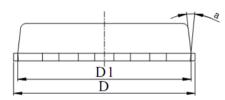


Package Mechanical Data-PDFN3333-8L-Single







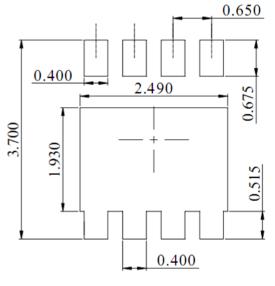


Front View

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. ALL DIMNESIONS IN MILLIMETER (ANNGLE IN DEGREE).
- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

DIM.	MILLIMETER				
DIM.	MIN.	NOM.	MAX.		
A	0.70	0.75	0.80		
b	0.25	0.30	0.35		
c	0.10	0.20	0.25		
D	3.00	3.15	3.25		
D1	2.95	3.05	3.15		
D2	2.39	2.49	2.59		
E	3.20	3.30	3.40		
E1	2.95	3.05	3.15		
E2	1.70	1.80	1.90		
e	0.65 BSC				
Н	0.30	0.40	0.50		
L	0.25	0.40	0.50		
a			15°		



DIMENSIONS:MILLIMETERS